

XL2012

#### **Features**

- Wide 8V to 40V input voltage range.
- Fixed 5V output voltage.
- Maximum 2.4A output current.
- Fixed 150KHz switching frequency.
- Internal optimize power MOSFET.
- High efficiency up to 92%.
- Built in output short shutdown function.
- Excellent line and load regulation.
- Built in thermal shutdown function.
- Built in current limit function.
- Available in SOP8L package.

# **Applications**

- Car Charger.
- Battery Charger.
- USB Power Supply.

#### **General Description**

The XL2012 is a 150 KHz fixed frequency PWM buck (step-down) DC/DC converter, capable of driving a 2.4A load with high efficiency, low ripple and excellent line and load regulation. Requiring a minimum number of external components, the regulator is simple to use and include internal frequency compensation and a fixed-frequency oscillator.

The XL2012 built in output short protection function. When short protection function happens, the chip will be shutdown. An internal compensation block is built in to minimize external component count.



Figure 1. Package Type of XL2012



XL2012

# **Pin Configurations**

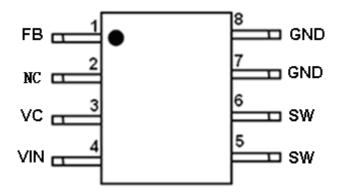


Figure 2. Pin Configuration of XL2012 (Top View)

# Table 1 Pin Description

Pin Number	Pin Name	Description
1	FB	Feedback Pin (FB). The feedback threshold voltage is 5V.
2	NC	No Connected.
3	VC	Internal Voltage Regulator Bypass Capacity. In typical system application, The VC pin connect a 1uf capacity to VIN.
4	VIN	Supply Voltage Input Pin. XL2012 operates from 8V to 40V DC voltage. Bypass Vin to GND with a suitably large capacitor to eliminate noise on the input.
5,6	SW	Power Switch Output Pin (SW). SW is the switch node that supplies power to the output.
7,8	GND	Ground Pin. Care must be taken in layout. This pin should be placed outside of the schottky diode to output capacitor ground path to prevent switching current spikes from inducing voltage noise into XL2012.



XL2012

## **Function Block**

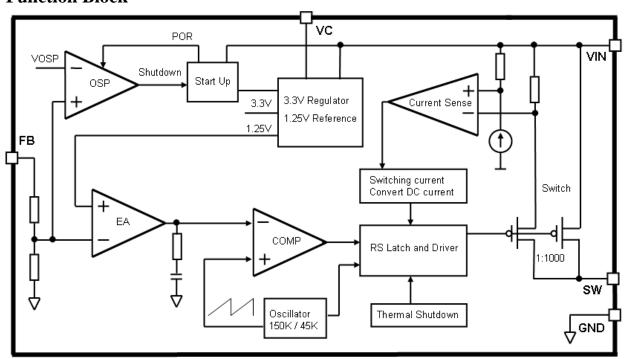


Figure 3. Function Block Diagram of XL2012

# **Typical Application Circuit**

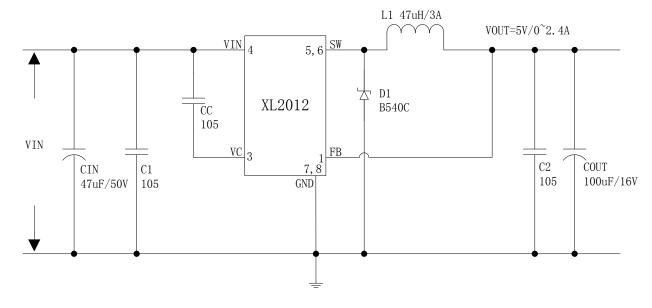


Figure 4. XL2012 Typical Application Circuit (VIN=8V~40V, VOUT=5V/2.4A)



XL2012

## **Ordering Information**

Order Information	Marking ID	Package Type	Packing Type Supplied As
XL2012E1	XL2012E1	SOP8L	2500/4000 Units on Tape & Reel

XLSEMI Pb-free products, as designated with "E1" suffix in the par number, are RoHS compliant.

## **Absolute Maximum Ratings (Note1)**

Parameter	Symbol	Value	Unit	
Input Voltage	Vin	-0.3 to 45	V	
Feedback Pin Voltage	V <sub>FB</sub> -0.3 to Vin		V	
Output Switch Pin Voltage	$V_{Output}$	V <sub>Output</sub> -0.3 to Vin		
Power Dissipation	$P_{D}$	Internally limited	mW	
Thermal Resistance (SOP8L)	D	100	C/W	
(Junction to Ambient, No Heatsink, Free Air)	$R_{JA}$	100		
Operating Junction Temperature	$T_{J}$	-40 to 125	C	
Storage Temperature	T <sub>STG</sub>	-65 to 150	C	
Lead Temperature (Soldering, 10 sec)	T <sub>LEAD</sub>	260	C	
ESD (HBM)		>2000	V	

**Note1:** Stresses greater than those listed under Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.



XL2012

## **XL2012 Electrical Characteristics**

 $T_a = 25 \,^{\circ}\text{C}$ ; unless otherwise specified.

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit	
System parameters test circuit figure4							
VFB	Feedback Voltage	Vin = 8V to 40V, Vout=5V Iload=0.5A to 2.4A	4.9	5	5.1	V	
Efficiency	ŋ	Vin=12V ,Vout=5V Iout=2.4A	- 89		-	%	

## **Electrical Characteristics (DC Parameters)**

Vin = 12V, GND=0V, Vin & GND parallel connect a 47uF/50V capacitor; Iout=500mA,  $T_a = 25\,^{\circ}\text{C}$ ; the others floating unless otherwise specified.

Parameters	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Input operation voltage	Vin		8		40	V
Quiescent Supply Current	$I_q$	V <sub>FB</sub> =Vin		4.7	10	mA
Output Short Supply Current	Iosp				5	mA
Oscillator Frequency	Fosc		128	150	173	KHz
Switch Current Limit	$I_{L}$	V <sub>FB</sub> =0		2.6		A
Output Power PMOS	Rdson	V <sub>FB</sub> =0V, Vin=12V, I <sub>SW</sub> =2.4A		60	80	mohm



XL2012

# **Typical System Application (VOUT=5V/2.4A)**

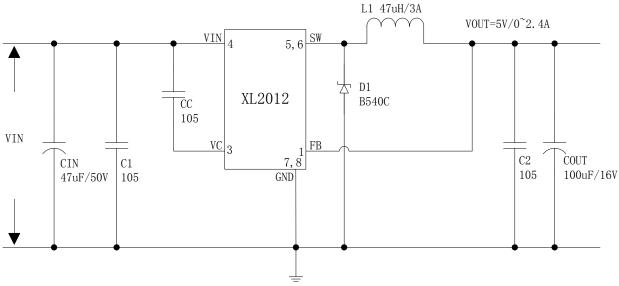


Figure 5. XL2012 System Parameters Test Circuit (VIN=8V~40V, VOUT=5V/2.4A)

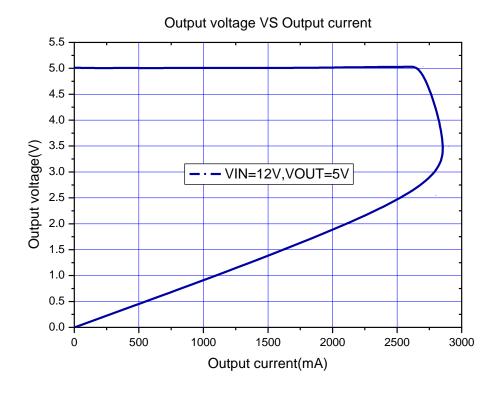


Figure 6. XL2012 System Output Constant Current Curve



XL2012

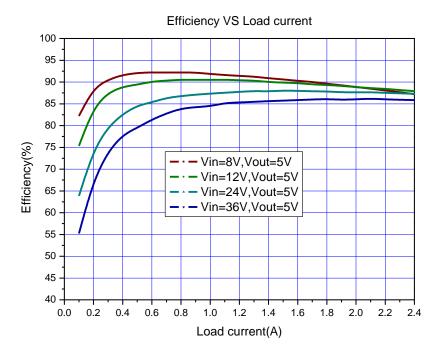


Figure 7. XL2012 System Efficiency Curve



XL2012

## Output short shutdown function description

The output short shutdown function is built in XL2012. The short protection circuit monitors the output voltage, whenever FB pin voltage is below 1.5V, the short circuit protection circuit is triggered, the converter will be shutdown, input current less than 5mA.

When the short fault is removed, if output load is floating, then converter will restart up, the output voltage will return to normal; if output load isn't floating, then converter must be power reset, the output voltage will comeback.

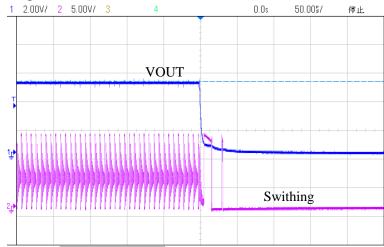


Figure 8. The converter will be shutdown when output short happen.

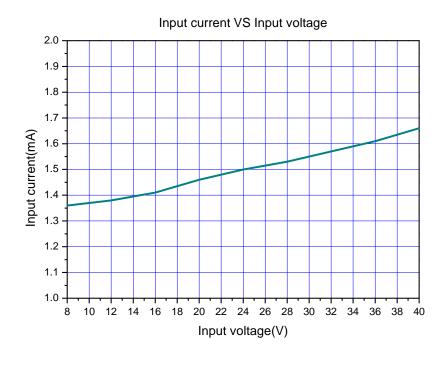


Figure 9. The input current curve when output short happen.



XL2012

# Package Information SOP8 Package Mechanical Dimensions

Unit: mm(inch) SOIC-8 4.700(0.185) 0.320(0.013) 1.350(0.053) 5.100(0.201) 1.750(0.069) 0.675(0.027) 0.725(0.029) 5.800(0.228) 1.270(0.050) 6.200(0.244) Ф 0.800(0.031) 0.100(0.004) R0.150(0.006) 0.300(0.012) 0.200(0.008) 1.000(0.039) 3.800(0.150) 4.000(0.157) 0.190(0.007) 0.330(0.013) 0.250(0.010) 0.510(0.020) 0.900(0.035) R0.150(0.006)

0.450(0.017) 0.800(0.031)



XL2012

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